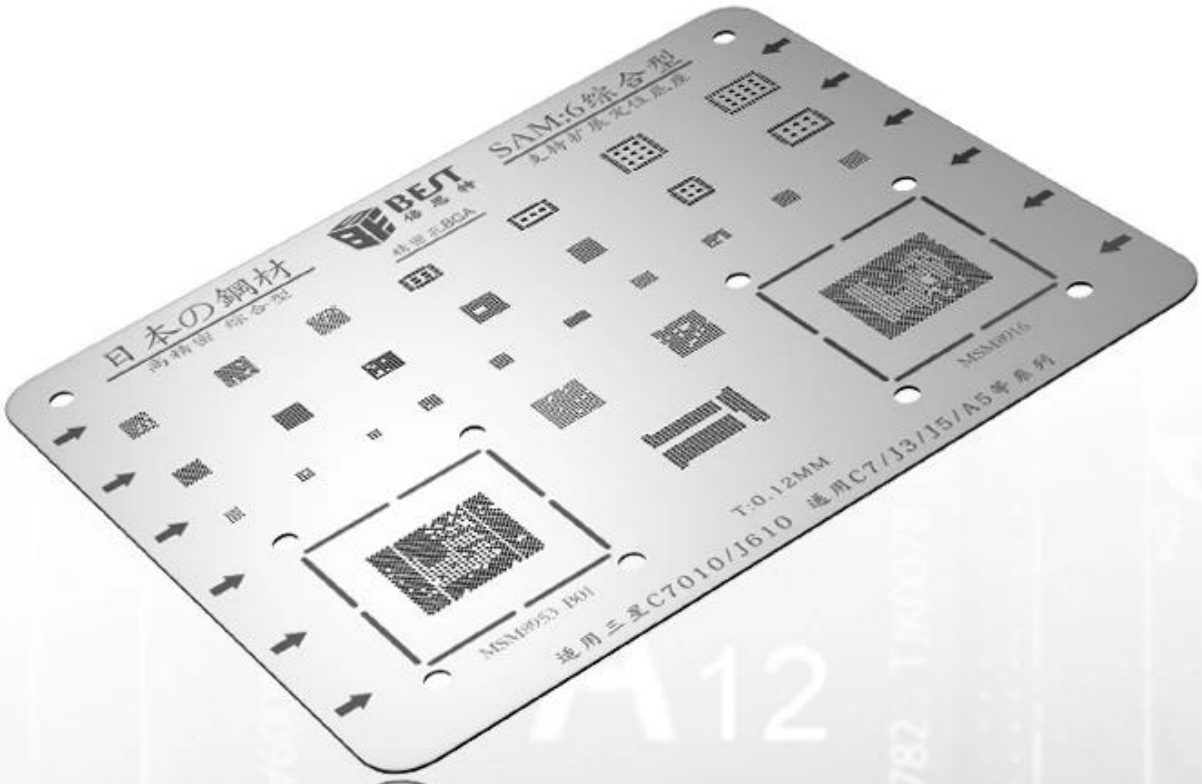
REBALLING STENCIL

— SAMSUNG CPU series —



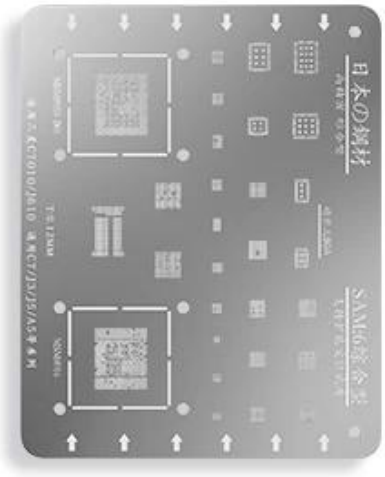
SEMI-ETCHING PROCESS

COOLING HOLE DESIGN

PRECISE ALIGNMENT

SQUARE HOLE

Product Usage



MATERIAL	Imported steel
BRAND	BESTOOL
PRODUCT NAME	Reballing Stencil
WEIGHT	7g
TYPE	Precise alignment Strong toughness Non-stick ti

▼PRODUCT CHARACTIERISTICS

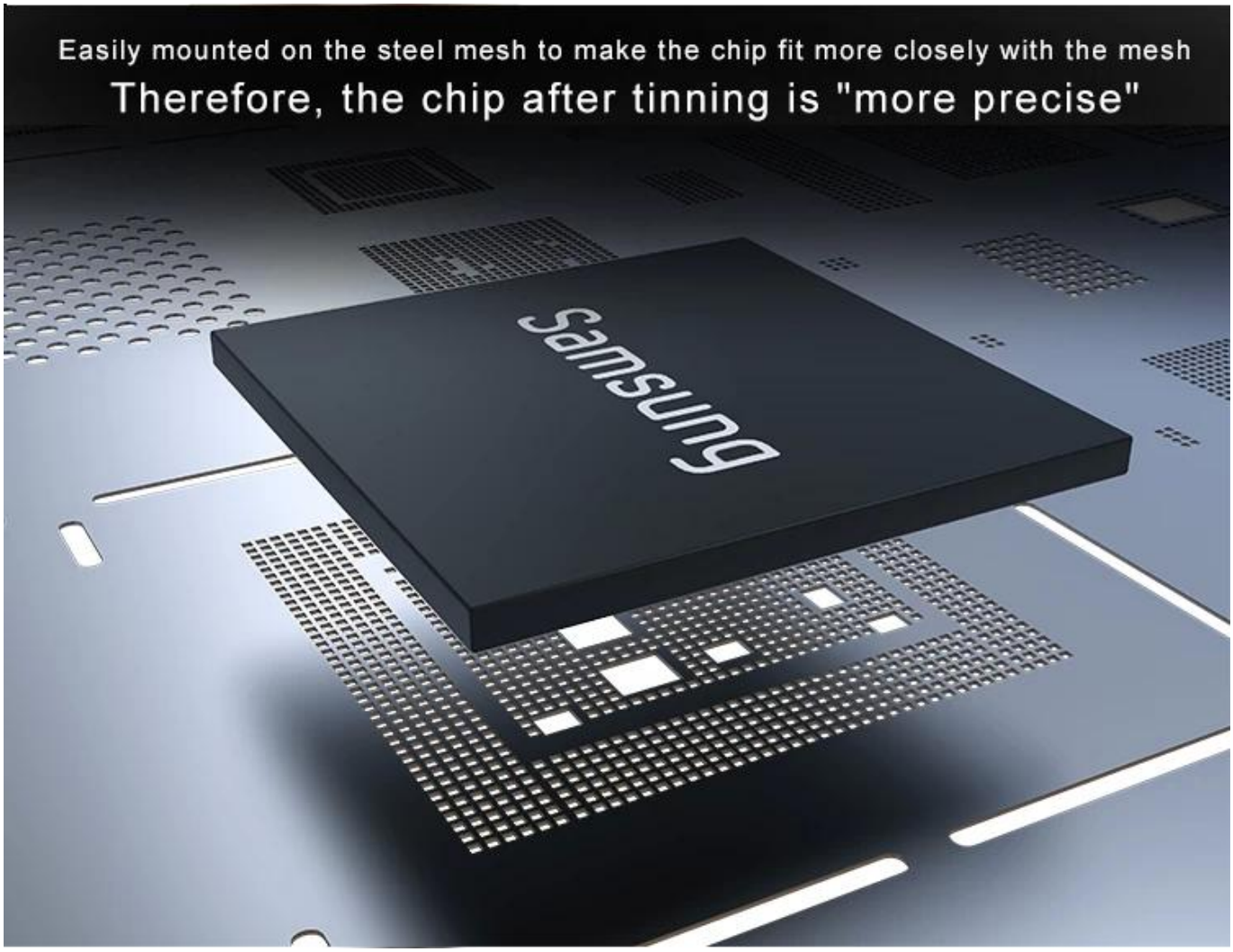
This product is used for BGA tinning repair of the SAMSUNG series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

PRODUCT INFORMATION

IMPORTED STEEL

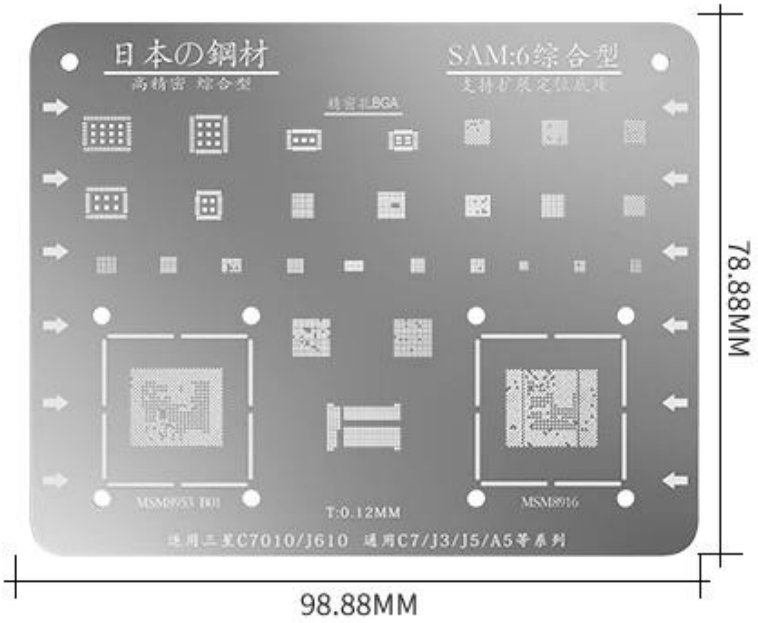
HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY
EXCELLENT FORGING PROCESSES,
BUT THE REAL CORE LIES IN THE
SELECTION OF DELICATE MATERIALS.


Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"
Samsung

Imported steel
Hard and wear resistant
Accurate to the hole

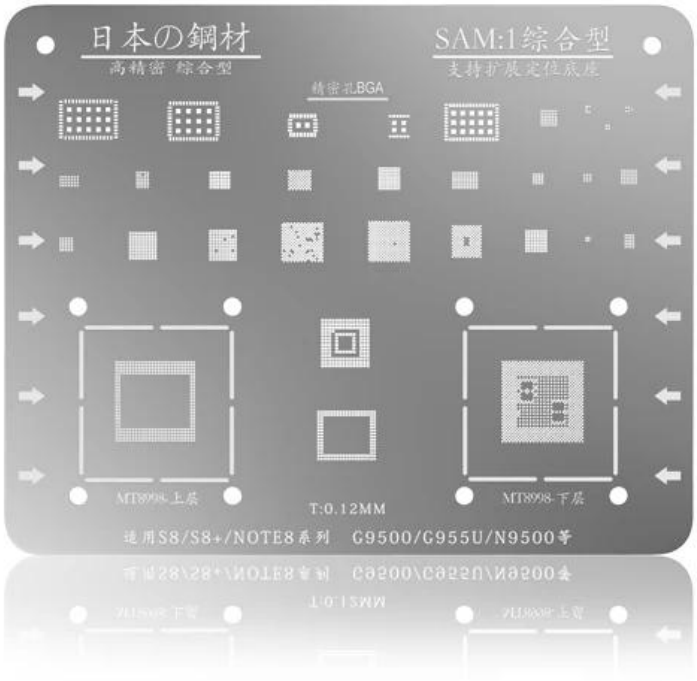
PRODUCT SIZE



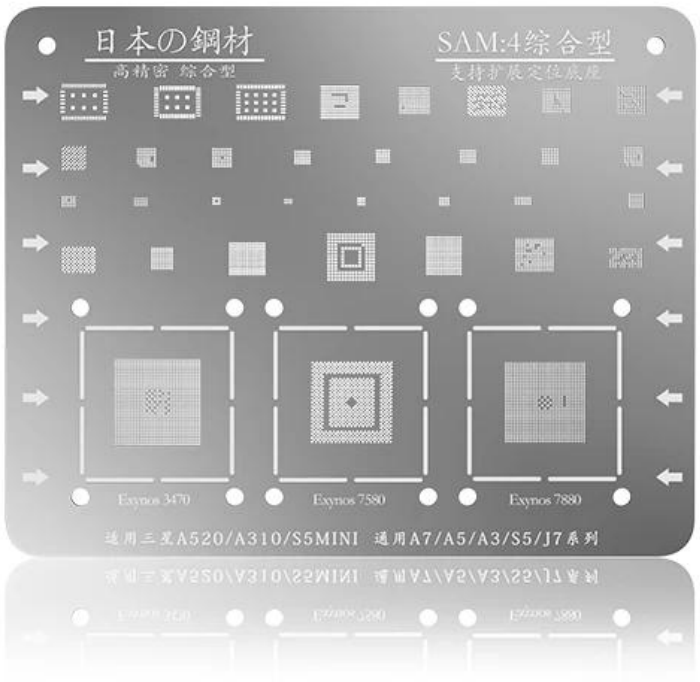
Thin to 0.12mm

Precise die-casting Iform heating

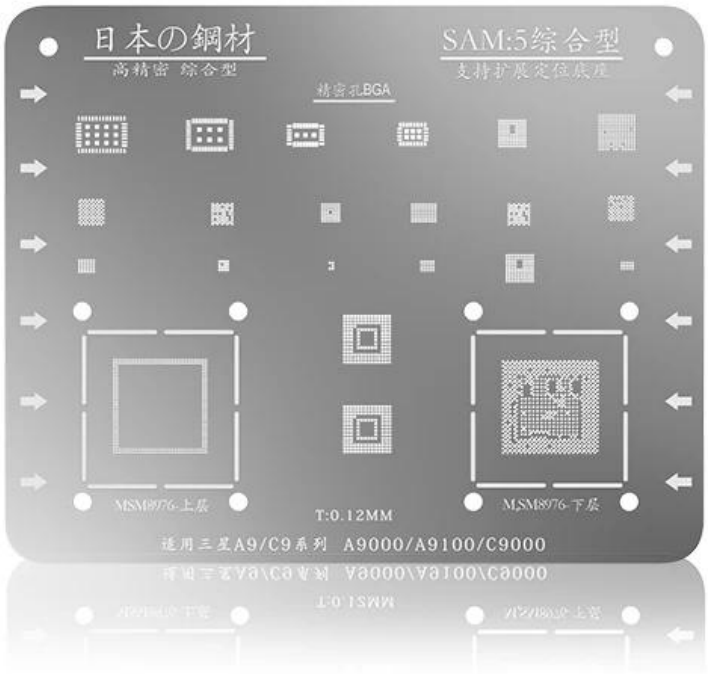
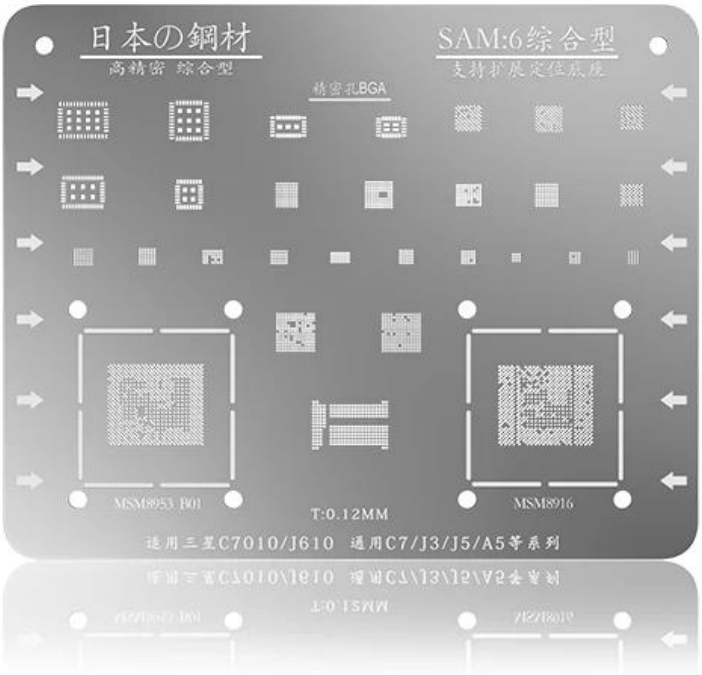
S8/S8+NOTE8



A520/A310/S5MINI General purposeA7/A3/S5/J7



A9/C9series A9000/A9100/C9000



C7010/J610 General purpose C7/J3/J5/A5